Characteristics STPS2545C

1 Characteristics

Table 2: Absolute ratings (limiting values, per diode, at 25 °C, unless otherwise specified)

Symbol	Parame	Value	Unit			
V _{RRM}	Repetitive peak reverse voltage			45	V	
I _{F(RMS)}	Forward rms current			30	Α	
	Average forward current $\delta = 0.5$,	T _C = 160 °C	Per diode	12.5	- A	
I _{F(AV)}	square wave	T _C = 155 °C	Per device	25		
I _{FSM}	Surge non repetitive forward current	t _p = 10 ms sinus	soidal	200	Α	
P _{ARM}	Repetitive peak avalanche power $t_p = 10 \mu s$, $T_j = 125 °C$			345	W	
T _{stg}	Storage temperature range			-65 to +175	°C	
Tj	Maximum operating junction temperature (1)			175	°C	

Notes:

Table 3: Thermal parameters

Symbol	Parameter	Max. value	Unit	
D	lunction to cons	Per diode	1.6	°C/W
Kth(j-c)	R _{th(j-c)} Junction to case		1.1	C/VV
R _{th(c)}	Coupling		0.6	°C/W

When the diodes 1 and 2 are used simultaneously:

 $\Delta T_i(diode\ 1) = P(diode\ 1) \times R_{th(j-c)}(Per\ diode) + P(diode\ 2) \times R_{th(c)}$

Table 4: Static electrical characteristics (per diode)

	<u> </u>						
Symbol	Parameter	Test conditions		Min.	Тур.	Max.	Unit
I _R ⁽¹⁾	Deverage leader as assument	T _j = 25 °C	VR = VRRM	-		125	μΑ
IR''	Reverse leakage current	T _j = 125 °C		-	9	25	mA
V _F ⁽¹⁾	Forward voltage drop	T _j = 125 °C	I _F = 12.5 A	-	0.50	0.57	
		T _j = 25 °C	I _F = 25 A	-		0.84	V
		T _j = 125 °C		-	0.65	0.72	

Notes

(1)Pulse test: t_p = 380 μs, δ < 2%

To evaluate the conduction losses, use the following equation:

$$P = 0.42 \text{ x } I_{F(AV)} + 0.012 \text{ x } I_{F^2(RMS)}$$

 $^{^{(1)}(}dP_{tot}/dT_j) < (1/R_{th(j-a)})$ condition to avoid thermal runaway for a diode on its own heatsink.

STPS2545C Characteristics

1.1 Characteristics (curves)

Figure 1: Conduction losses versus average current, per diode)

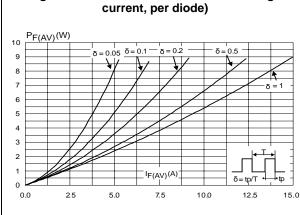


Figure 2: Average forward current versus ambient temperature (δ = 0.5, per diode)

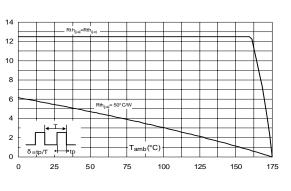


Figure 3: Normalized avalanche power derating versus pulse duration (T_j = 125 °C)

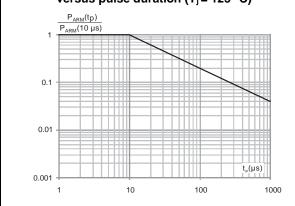


Figure 4: Relative variation of thermal impedance junction to case versus pulse duration

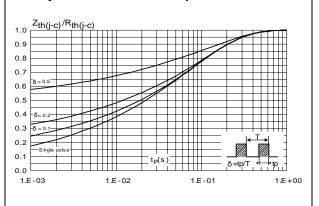


Figure 5: Reverse leakage current versus reverse voltage applied (typical values, per diode)

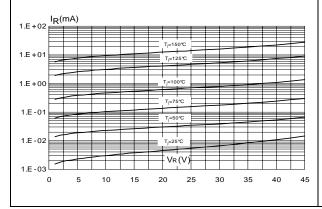
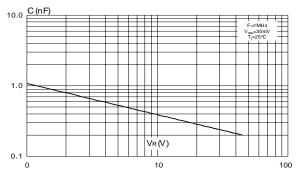


Figure 6: Junction capacitance versus reverse voltage applied (typical values, per diode)



Characteristics STPS2545C

Figure 7: Forward voltage drop versus forward current (per diode) 100 10 VF(V) 0.2

0.6

0.8

1.0

1.2

1.4

0.0

versus copper surface under tab 70 Epoxy printed board FR4, copper thickness 60 50 40 30 20 10 0 10 15 20 30 40 0 $S_{Ou}(cm^{2})$

Figure 8: Thermal resistance junction to ambient

4/11 DocID8736 Rev 5 STPS2545C Package information

2 Package information

In order to meet environmental requirements, ST offers these devices in different grades of ECOPACK® packages, depending on their level of environmental compliance. ECOPACK® specifications, grade definitions and product status are available at: **www.st.com**. ECOPACK® is an ST trademark.

- Cooling method: by conduction (C)
- Epoxy meets UL 94,V0
- Recommended torque value: 0.55 N·m (for TO-220AB)
- Maximum torque value: 0.7 N·m (for TO-220AB)

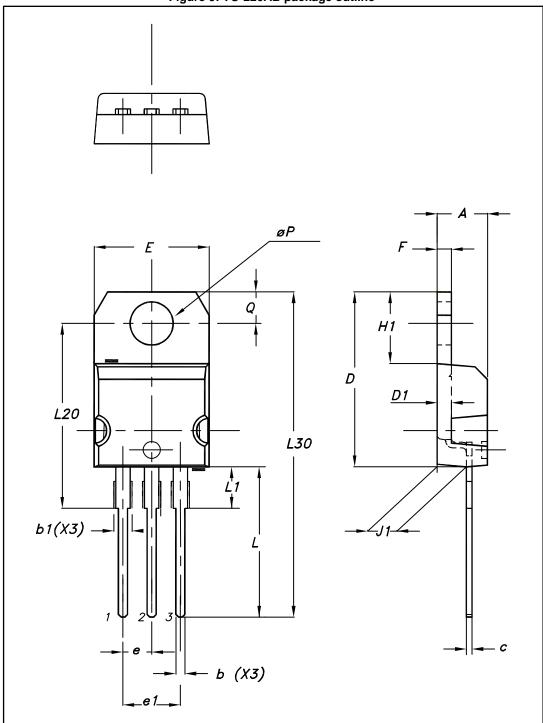


DocID8736 Rev 5 5/11

Package information STPS2545C

2.1 TO-220AB package information

Figure 9: TO-220AB package outline



47/

STPS2545C Package information

Table 5: TO-220AB package mechanical data

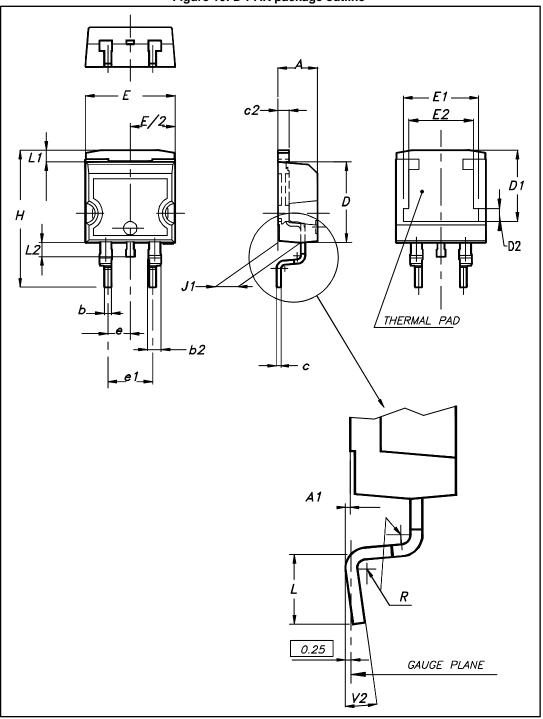
	Dimensions				
Ref.	Millimeters		Inches		
	Min.	Max.	Min.	Max.	
А	4.40	4.60	0.173	0.181	
b	0.61	0.88	0.240	0.035	
b1	1.14	1.70	0.045	0.067	
С	0.48	0.70	0.019	0.028	
D	15.25	15.75	0.600	0.620	
D1	1.27 typ.		0.050 typ.		
Е	10.00	10.40	0.394	0.409	
е	2.40	2.70	0.094	0.106	
e1	4.95	5.15	0.195	0.203	
F	1.23	1.32	0.048	0.052	
H1	6.20	6.60	0.244	0.260	
J1	2.40	2.72	0.094	0.107	
L	13.00	14.00	0.512	0.551	
L1	3.50	3.93	0.138	0.155	
L20	16.40 typ.		0.646 typ.		
L30	28.90 typ.		1.138 typ.		
θР	3.75	3.85	0.148	0.152	
Q	2.65	2.95	0.104	0.116	



Package information STPS2545C

2.2 D²PAK package information

Figure 10: D²PAK package outline





This package drawing may slightly differ from the physical package. However, all the specified dimensions are guaranteed.

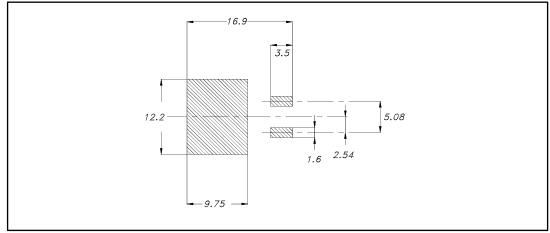
8/11 DocID8736 Rev 5

STPS2545C Package information

Table 6: D²PAK package mechanical data

	Dimensions				
Ref.	Millimeters		Inches		
	Min.	Max.	Min.	Max.	
А	4.36	4.60	0.172	0.181	
A1	0.00	0.25	0.000	0.010	
b	0.70	0.93	0.028	0.037	
b2	1.14	1.70	0.045	0.067	
С	0.38	0.69	0.015	0.027	
c2	1.19	1.36	0.047	0.053	
D	8.60	9.35	0.339	0.368	
D1	6.90	8.00	0.272	0.311	
D2	1.10	1.50	0.043	0.060	
Е	10.00	10.55	0.394	0.415	
E1	8.10	8.90	0.319	0.346	
E2	6.85	7.25	0.266	0.282	
е	2.54 typ.		0.100		
e1	4.88	5.28	0.190	0.205	
Н	15.00	15.85	0.591	0.624	
J1	2.49	2.90	0.097	0.112	
L	1.90	2.79	0.075	0.110	
L1	1.27	1.65	0.049	0.065	
L2	1.30	1.78	0.050	0.070	
R	0.4	0.4 typ.		15	
V2	0°	8°	0°	8°	

Figure 11: D²PAK recommended footprint (dimensions in mm)



Ordering information STPS2545C

3 Ordering information

Table 7: Ordering information

Order code	Marking	Package	Weight	Base qty.	Delivery mode
STPS2545CT	STPS2545CT	TO-220AB	1.95 g	50	Tube
STPS2545CG-TR	STPS2545CG	D²PAK	1.38 g	1000	Tape and reel

4 Revision history

Table 8: Document revision history

Date	Revision	Changes	
July-2003	2A	Last release.	
21-Jun-2010	3	Updated ECOPACK statement.	
28-jun-2012	4	Corrected typographical error in Table 3.	
12-May-2017	5	Removed TO-220FPAB package.	

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